

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S36	9	S35 not (S1 S4 S8 S14 S25)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:47
S37	3579	(257/778-779).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/01 19:47
S38	67	S37 and (attac\$3 affix\$3 bind\$3 connect\$3 coupl\$3, fasten\$3 fix\$3 secur\$3)with (IC integrated near1 circuit chip microelectronic die semiconductor) with (angle slop\$3 inclinat\$ diagonal\$3 not near2 parallel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 20:14
S39	30	S38 not (S1 S4 S8 S14 S25 S35)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 19:48
S43	2499	((attac\$3 affix\$3 bind\$3 connect\$3 coupl\$3, fasten\$3 fix\$3 secur\$3)and (IC integrated near1 circuit chip microelectronic die semiconductor) and (diagonal\$3 angle slop\$3 inclinat\$ diagonal\$3 not near2 parallel) and (substrate board bga pcb interposer tape insulat\$3 near1 layer)).clm.	US-PGPUB	OR	ON	2006/03/01 20:15
S44	54047	((attac\$3 affix\$3 bind\$3 connect\$3 coupl\$3, fasten\$3 fix\$3 secur\$3)and(IC integrated near1 circuit chip microelectronic die semiconductor) and (solder bump ball c4 contact electrode) and (substrate board bga pcb interposer tape insulat\$3 near1 layer)).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/01 20:16
S45	20025	((attac\$3 affix\$3 bind\$3 connect\$3 coupl\$3, fasten\$3 fix\$3 secur\$3)and(IC integrated near1 circuit chip microelectronic die semiconductor) and (solder bump ball c4 contact electrode) and (substrate board bga pcb interposer tape insulat\$3 near1 layer)).clm.	US-PGPUB	OR	ON	2006/03/01 20:17

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S46	2059	((attac\$3 affix\$3 bind\$3 connect\$3 coupl\$3, fasten\$3 fix\$3 secur\$3)and(IC integrated near1 circuit chip microelectronic die semiconductor) and (solder bump ball c4 contact electrode) and (substrate board bga pcb interposer tape insulat\$3 near1 layer) and (seal\$3 underfill)).clm.	US-PGPUB	OR	ON	2006/03/01 20:27
S48	273	((attac\$3 affix\$3 bind\$3 connect\$3 coupl\$3, fasten\$3 fix\$3 secur\$3)and(IC integrated near1 circuit chip microelectronic die semiconductor) and (solder bump ball c4 ) and (substrate board bga pcb interposer tape insulat\$3 near1 layer) and ( underfill)).clm.	US-PGPUB	OR	ON	2006/03/01 20:38
S49	1	("20040047539"  "3811186"  "5056215"  "5173220"  "5220200"  "5278442"  "5484314"  "5700715"  "5705117"  "6251488"  "6259962"  "6268584"  "6287895"  "6301251"  "6326698"  "6410366"  "6461881"  "6506671"  "6525408"  "6544821"  "6548897"  "6569753"  "6630385"  "6649444"  "6740962").PN.	US-PGPUB	OR	ON	2006/03/01 20:27
S50	25	("20040047539"  "3811186"  "5056215"  "5173220"  "5220200"  "5278442"  "5484314"  "5700715"  "5705117"  "6251488"  "6259962"  "6268584"  "6287895"  "6301251"  "6326698"  "6410366"  "6461881"  "6506671"  "6525408"  "6544821"  "6548897"  "6569753"  "6630385"  "6649444"  "6740962").PN.	US-PGPUB; USPAT	OR	ON	2006/03/01 20:27
S51	32	("20020185746"  "20030022462"  "20030045028"  "3811186"  "5056215"  "5173220"  "5264061"  "5278442"  "5484314"  "5633535"  "5705117"  "5841198"  "6140707"  "6165885"  "6255143"  "6281577"  "6313522"  "6313650"  "6316286"  "6358776"  "6399421"  "6420213"  "6440774"  "6444489"  "6461881").PN. OR ("6649444").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/01 20:36
S52	15	("3811186"  "5056215"  "5173220"  "5264061"  "5278442"  "5484314"  "5633535"  "5705117"  "5841198"  "6140707"  "6165885"  "6255143"  "6281577"  "6313522"  "6313650").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/01 20:58
S53	151	and\$1j\$2.xa.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/01 20:58
S54	3	("5115545"  "6269999"  "6559523").PN. OR ("6978534").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/01 20:59

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S55	20	("2756483"   "3204327"   "3657790"   "3729966"   "3811182"   "3946484"   "4095095"   "4340617"   "4718967"   "4749120").PN. OR ("5115545"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/01 21:00
S56	25	("4831724"   "5037780"   "5115545"   "5205032"   "5214308"   "5232532"   "5316610"   "5385632"   "5722160"   "5739053"   "5785234"   "5802712"   "5813115"   "5816478"   "5829125").PN. OR ("6000127"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/01 21:03
S57	3	("6069024" "6404062" "6576495"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/01 21:03
S58	12	("5962925").PN. OR ("6069024"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/01 21:12
S59	1	"20020043711".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/03/01 21:12